

# Dressing Requirements & Instructions per Application



## *Recommended Dressing per Application*

### General:

Substrate matrices and quality requirements may vary and be different from customer to customer.

The ADT recommended dressing procedures are general / generic recommendations based on years of experience in the market place. They are a good starting point for each application.

Final optimization of the dressing procedure should be performed at the customer site in a production mode

# Recommended Dressing per Application

## Application - Plastic BGA

Most BGA type applications require no specific dressing.  
Customers are starting to dice on production wafers, some at top production feed rate and some by an override process.

Blade Used – For tape mounting – Metal Sintered – ADT Matrices –95, 29, 62, 02  
For tapeless mounting – Metal Sintered – ADT Matrix 42

Override recommendation:

Override media – Production BGA substrate

Recommended override parameters:-

Spindle speed – Production speed 30-40Krpm

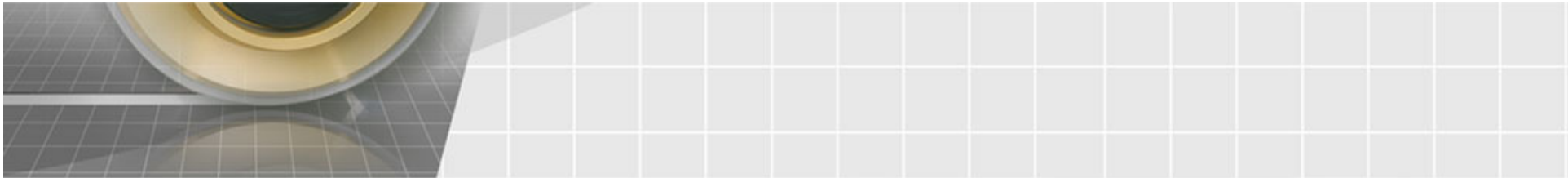
Feed rate – Start at 10mm/sec going up by 5mm/sec increments, making 5x cuts at each feed rate, going up to production speed.

Cut depth – Use production depth

Index – Use substrate index

Note – Perform height only after the dressing / override process is completed





## Application - QFN – H.E. – Lead / Tin (Matte) (Pb / Sn) coating

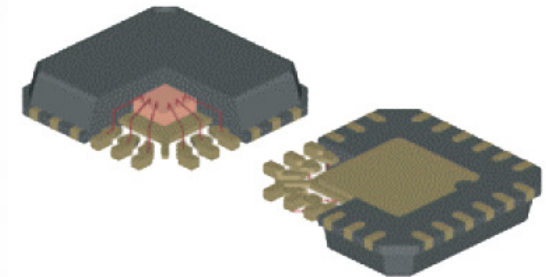
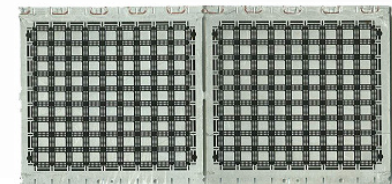
Blade used – Resin –E- & -T-series

Dressing media – Silicon Carbide – 320 mesh

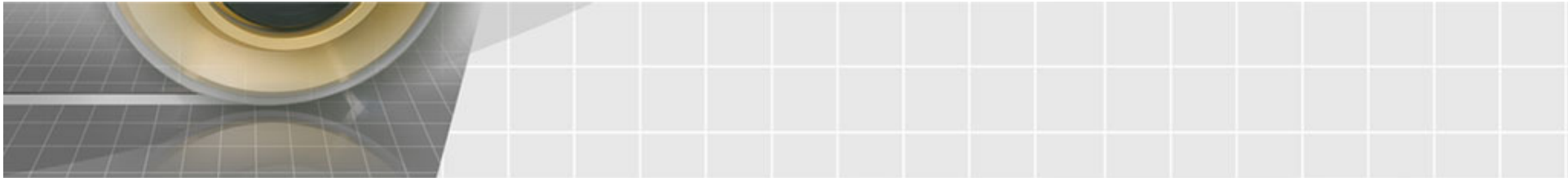
Dressing media geometry – 90 x 25 x 3mm

Dressing media P/N – 00767-0320-003

<u>Dressing parameters</u>	Process	
	2”	3”
Spindle speed – (Krpm)	22	15
Feed rate – mm/sec	10 / 10x cuts	10 / 10x cuts
	20 / 5x cuts	20 / 5x cuts
	40 / 5x cuts	40 / 5x cuts
	60 / 5x cuts	60 / 5x cuts
	80 / 5x cuts	80 / 5x cuts
Cut depth – (mm)	Production + 0.2	Production + 0.2
Cut length – (Meters)	~1-1.5	~1-1.5
Index –	2x blade Thick.	2x blade Thick.



Note – Perform height only after the dressing process is completed



## Application - QFN – H.E. – Nickel Palladium (Ni / Pd) coating

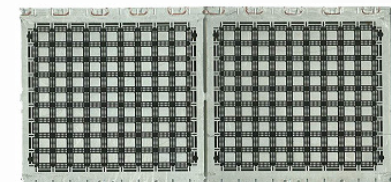
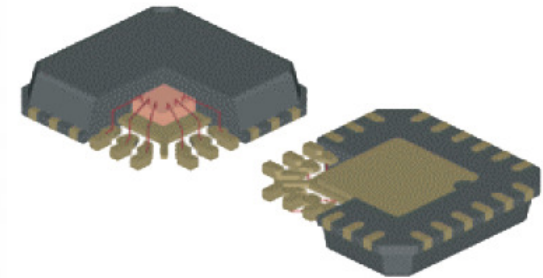
Blade used – Resin –E- & -T- series

Dressing media – Silicon Carbide – 320 mesh

Dressing media geometry – 90 x 25 x 3mm

Dressing media P/N – 00767-0320-003

<u>Dressing parameters</u>	Process	
	2”	3”
Spindle speed – (Krpm)	22	15
Feed rate – mm/sec	10 / 10x cuts	10 / 10x cuts
	20 / 5x cuts	20 / 5x cuts
	40 / 5x cuts	40 / 5x cuts
	60 / 5x cuts	60 / 5x cuts
	80 / 5x cuts	80 / 5x cuts
Cut depth – (mm)	Production + 0.2	Production + 0.2
Cut length – (Meters)	~1-1.5	~1-1.5
Index –	2x blade Thick.	2x blade Thick.



Note – Perform height only after the dressing process is completed



## Application – Power QFN

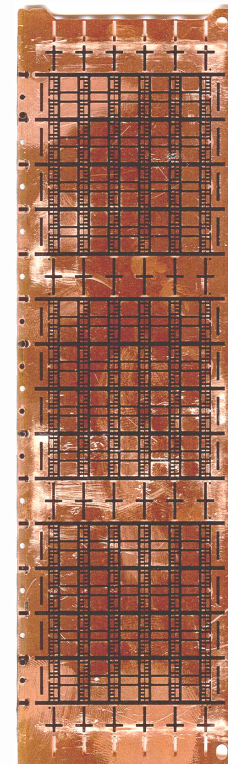
Blade used – Resin –E- series

Dressing media – Silicon Carbide – 320 mesh

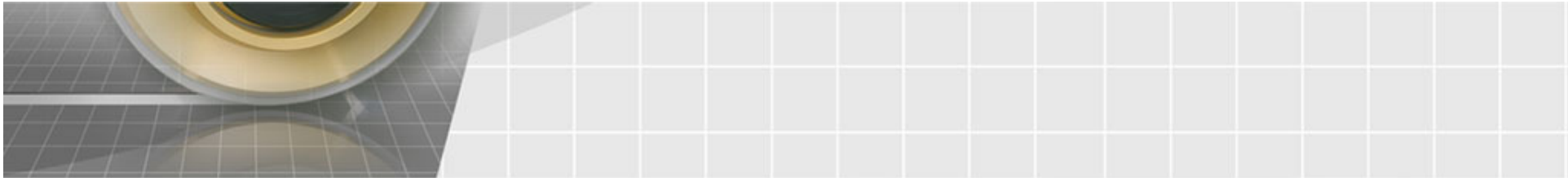
Dressing media geometry – 90 x 25 x 5mm

Dressing media P/N – 00767-0320-005

<u>Dressing parameters</u>	Process
	3”
Spindle speed – (Krpm)	12-16
Feed rate – mm/sec	10 / 10x cuts
	20 / 10x cuts
	40 / 10x cuts
Cut depth – (mm)	Production + 0.2
Cut length – (Meters)	~1-1.5
Index –	2x blade Thick.



Note – Perform height only after the dressing process is completed



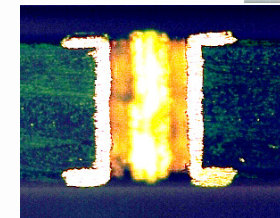
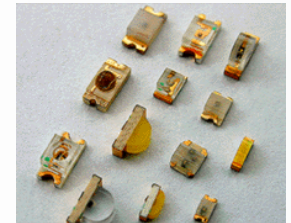
## Application – PCB (LED Packages)

Blade used – Nickel Serrated, 2” O.D. x “T”, “V” & “Z” matrices  
 x 10, 13, & 17mic. Grit x .003”-.008” thick

Dressing media – Green Silicon Car. 600mesh

Dressing media geometry - 90 x 25 x 2mm or 3mm

Dressing media P/N – 767-0600-002 or -003



<u>Dressing parameters:-</u>	<b>Process</b>
Spindle speed –	25-35Krpm
Feed rate –	10mm/sec 3x cuts, 20mm/sec 3x cuts, 40mm/sec 3x cuts 60mm/sec 3x cuts, 80mm/sec 3x cuts, 100mm/sec 3cuts
Cut depth -	Production + 0.2mm
Cut length –	~0.5meter
Index –	2x blade Thick.

**Note – Perform height only after the dressing process is complete**



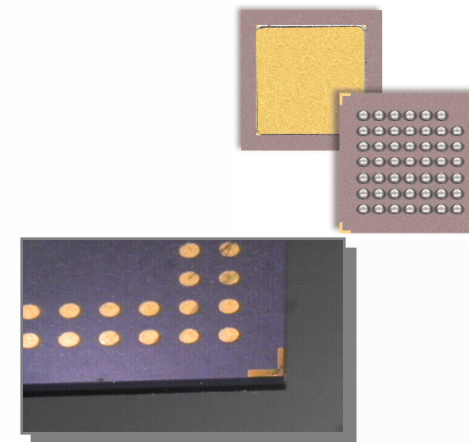
## Application – Ceramic BGA

Blade used - Resin, 2” or 4” O.D. X Matrices K or R x  
45 – 75mic diamond grit x .006” - .020” thick

Dressing media – Green Silicon Car. 600mesh

Dressing media geometry - 90 x 25 x 2mm or 3mm

Dressing media P/N – 767-0600-002 or -003



<u>Dressing parameters:-</u>	<b>2” O.D.</b>	<b>4” O.D.</b>
Spindle speed –	25 – 30Krpm	8 – 12Krpm
Feed rate –	2mm/sec 2x cuts, 4mm/sec 2x cuts, 6mm/sec 2x cuts 8mm/sec 2x cuts, 10mm/sec 2x cuts	
Cut depth -	Production + 0.2mm	
Cut length –	250mm	
Index –	Blade thickness x 2	

**Note – Perform height only after the dressing process is completed**



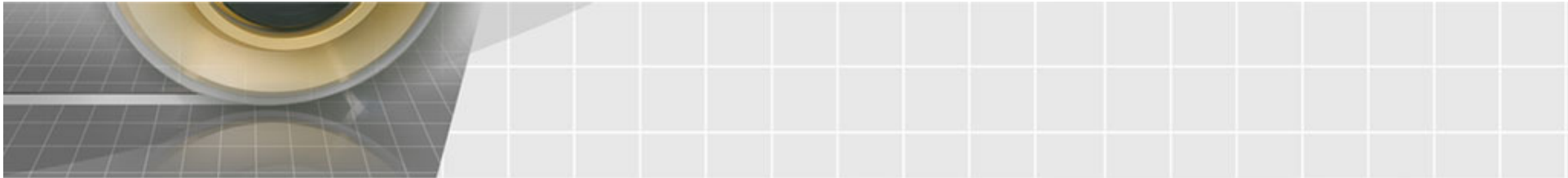


## Glass Applications general:

The market faces many glass applications with different thickness and material variations.

The following are general dressing recommendations. For special glass coatings or surface finishes consult the factory.

Glass up to 1mm thick can be diced with both resin & metal Sintered blades. Glass over 1mm we recommend to use resin type blades.



## Application – Glass using resinoid blades

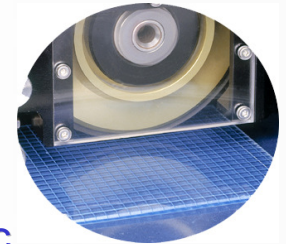
Blade used – Resin Matrices QUP, QKP & QIP x 2", 3" & 4" O.D  
 15-45mic. diamond grit x .003" - .020" thick

Dressing media – Green Silicon Car. 600mesh – 320 for grits over 30mic

Dressing media geometry - 90 x 25 x 2mm or 3mm or 5mm

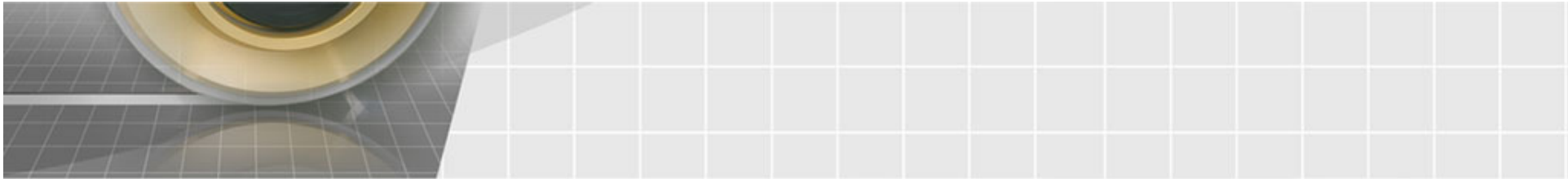
Dressing media P/N – 767-0600-002 or -003 or – 005

767-0320-003 or -005 - for over 30mic grit



<u>Dressing parameters:-</u>	Glass thickness range							
	Up to 0.5mm		0.5 to 1mm		1 – 2mm		2 – 4mm	
Spindle Dia.	2"	4"	2"	4"	2"	4"	2"	4"
Spindle speed – Krpm	20-30	8-12	20-30	8-12	18-25	8-12	18-25	8-12
Feed rate – mm/sec, cut / F.R	2, 4, 6 x 2 cuts		2, 4, 6 x 2 cuts		2, 4, 6, x 2 cuts		1, 2, 3, 4, 5, 2 cuts	
Cut depth -	Pro. Sub.+0.2mm		Pro. Sub.+0.2mm		Pro. Sub.+0.2mm		Pro. Sub.+0.2mm	
Index –	Blade thick. x 2		Blade thick. x 2		Blade thick. x 2		Blade thick. x 2	

**Note – Perform height only after the dressing process is completed**



## **Application – Glass using metal sintered blades**

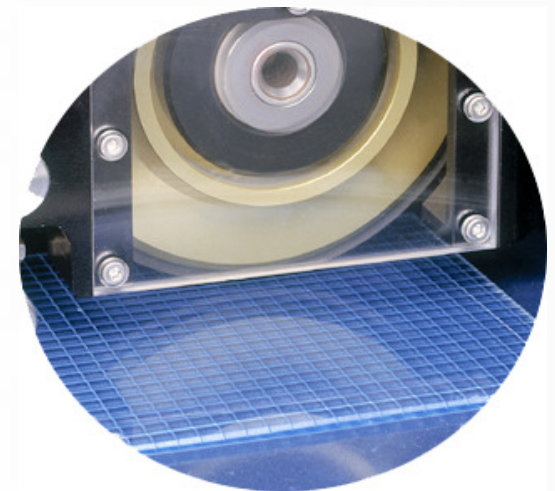
Blade used – Sintered matrices –M55, -M96 x 2” O.D.

10, 13, 17, 25, 30mic. diamond grit x .003” - .010” thick

Dressing media – Green Silicon Car. 600mesh

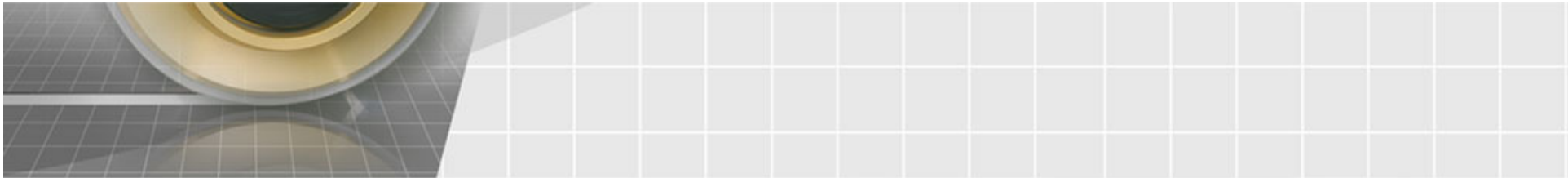
Dressing media geometry - 90 x 25 x 2mm or 3mm or 5mm

Dressing media P/N – 767-0600-002 or -003 or – 005



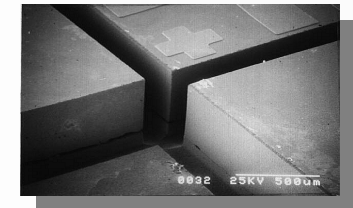
<u>Dressing parameters:-</u>	Glass thickness range	
	Up to 0.5mm	0.5 to 1mm
Spindle Dia.	2”	2”
Spindle speed – Krpm	20	20
Feed rate – mm/sec, cut / F.R	2,3,4,5, 6 x 2 cuts	2, 4, 5, 6 x 2 cuts
Cut depth -	Pro. Sub.+0.2mm	Pro. Sub.+0.2mm
Index –	Blade thick. x 2	Blade thick. x 2

**Note – Perform height only after the dressing process is completed**



## Application – Hard Alumina

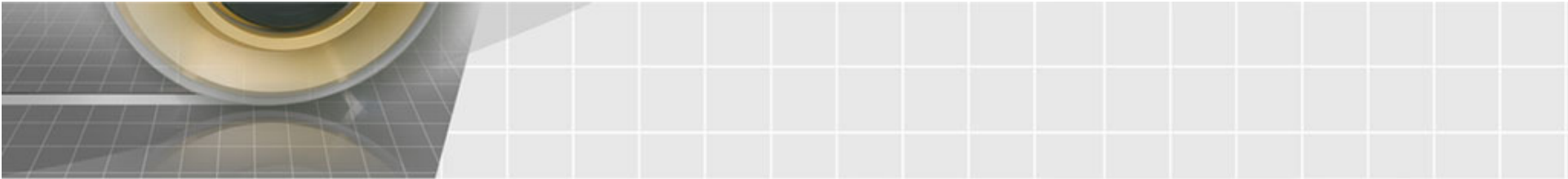
Blade used – Resin Matrices KUP, RUP x 2", & 4" O.D  
 45 - 88mic. diamond grit x .006" - .020" thick  
 Dressing media – Green Silicon Car. 320mesh  
 Dressing media geometry - 90 x 25 x 2mm or 3mm or 5mm  
 Dressing media P/N – 767-0320-002 or -003 or – 005



Dressing parameters:-	Glass thickness range							
	Up to 0.5mm		0.5 to 1mm		1 – 2mm		2 – 4mm	
Spindle Dia.	2"	4"	2"	4"	2"	4"	2"	4"
Spindle speed – Krpm	18-30	8-12	18-30	8-12	18-30	8-12	18-30	8-12
Feed rate – mm/sec, cut / F.R	2, 4, 6, 8 x 2 cuts		2, 4, 6, 8 x 2 cuts		2, 4, 6, 8 x 2 cuts		2, 4, 6, 8 x 2 cuts	
Cut depth -	Pro. Sub.+0.2mm		Pro. Sub.+0.2mm		Pro. Sub.+0.2mm		Pro. Sub.+0.2mm	
Index –	Blade thick. x 2		Blade thick. x 2		Blade thick. x 2		Blade thick. x 2	

Note – Perform height only after the dressing process is completed





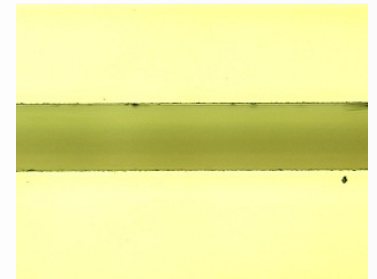
## Application – Quartz (SAW filters others)

Blade used – Resinoid 2” – Matrices KUP, QUP x 30-45mic. grit  
x .006” - .012” thick

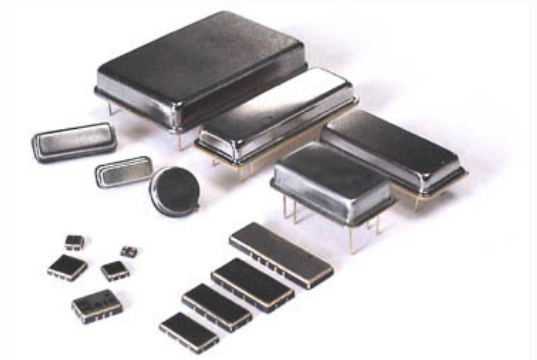
Dressing media – Green Silicon Car. 600mesh

Dressing media geometry - 90 x 25 x 2mm or 3mm

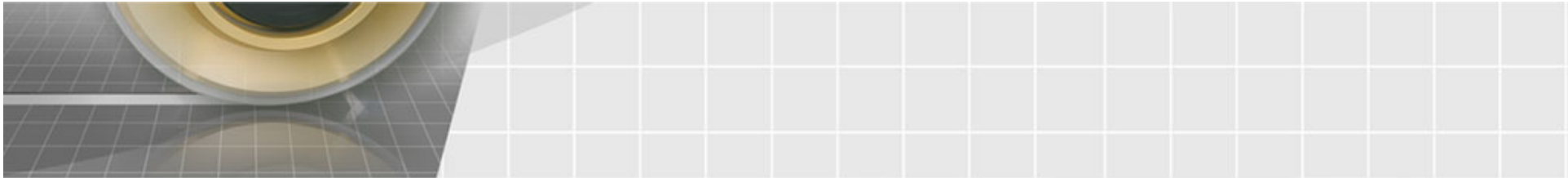
Dressing media P/N – 767-0600-002 or -003



<u>Dressing parameters:-</u> Spindle Dia. Spindle speed – Krpm Feed rate – mm/sec, X cuts / F.R Cut depth - Index –	Quartz thickness range	
	0.2 - 0.5mm	0.5 to 1mm
	2”	2”
	18 - 20	20 - 22
	1, 2, 3, 4, 5, x 2 cuts	1, 2, 4, 5, x 2 cuts
	Pro. Sub.+0.2mm	Pro. Sub.+0.2mm
	Blade thick. x 2	Blade thick. x 2



Note – Perform height only after the dressing process is completed



## Application – LiNbO3 & LiTaO3

Blade used - Nickel 2” O.D. x 3-6 & 4-8mic. Grit x .002”-.003” thick  
 - Resinoid 2” – Matrices QUP, QKP & KUP x 15 & 20mic. grit  
 x .003” - .006” thick

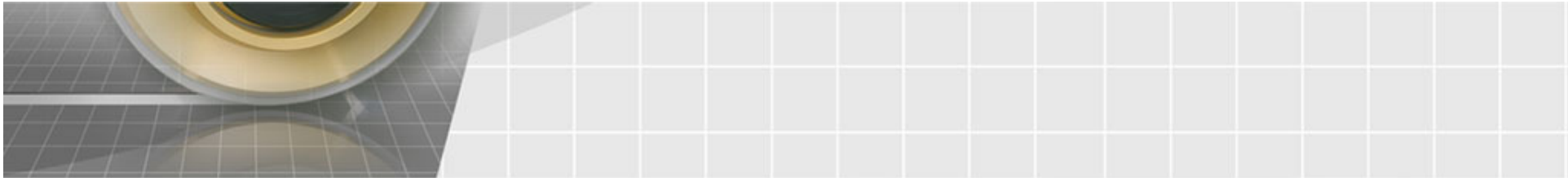
Dressing media – For Nickel – Silicon carbide (Dark) – 600 mesh  
 For Resinoid - Green Silicon Car. 600mesh

Dressing media geometry - Ni. - 75 x 75 x 1mm, Resin - 90 x 25 x 2mm or 3mm

Dressing media P/N – Ni. – 767-0000-001, Resin 767-0600-002 or -003

<u>Dressing parameters:-</u>	Nickel	Resinoid
Substrate thickness	0.2 - 1mm	0.2 - 2mm
Spindle Dia.	2”	2”
Spindle speed – Krpm	30Krpm	25-30Krpm
Feed rate – mm/sec, cut / F.R	2 x 10 cuts, 5x5 cuts & 8 x 1cut	2 x 2 cuts, 4 x 2 cuts, 8 x 2cuts
Cut depth -	.002” .005” Pr.+ 0.2mm	Production + 0.2mm
Index –	Blade thick. x 2	Blade thick. x 2

**Note – Perform height only after the dressing process is completed**



**Application – LTCC**

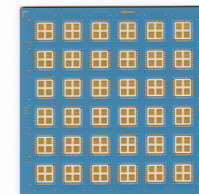
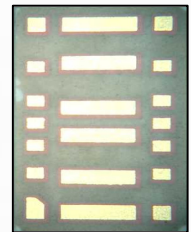
Blade used – Sintered 2” O.D. Matrices M94 & M50 x 15 - 35mic. Grit x .002”-.003”thick

Resinoid 2” – Matrices QUP, QKP & KUP x 35-53mic. grit x .006” - .008” thick

Dressing media – For Sintered – Green Silicon carbide 600 mesh  
 - For Resinoid - Green Silicon Car. 320 mesh

Dressing media geometry - 90 x 25 x 2mm or 3mm

Dressing media P/N – Sintered - 767-0600-002 or -003, Resin 767-0320-002 or -003



<u>Dressing parameters:-</u>	M. Sintered	Resinoid
Substrate thickness	0.2 - 2mm	0.5 - 2mm
Spindle Dia.	2”	2”
Spindle speed – Krpm	32-38	28-30
Feed rate – mm/sec, cut / F.R	2 x10cuts, 4x5cuts & 6x 5cuts	5 x 5 cuts, 8 x5 cuts & 5 x 1cut
Cut depth -	Pro. Sub.+0.2mm	.002” .005” Pr.+ 0.2mm
Index –	Blade thick. x 2	Blade thick. x 2

**Note – Perform height only after the dressing process is completed**





## Application – HTCC

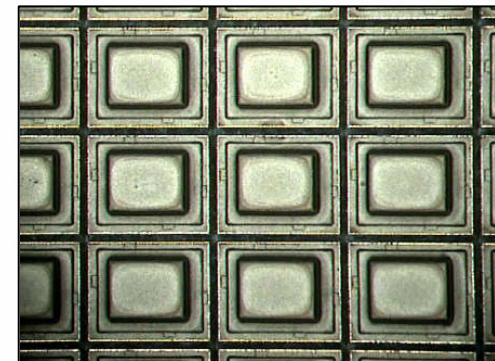
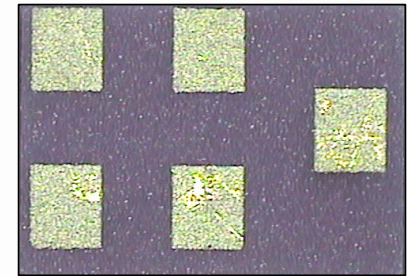
Blade used – Sintered – 2“ O.D. Matrices M94 & M50 x 35-50mic. Grit  
x .005” - .008” thick

Dressing media – Green Silicon Carbide – 320 mesh

Dressing media geometry – 90 x 25 x 2 or 3mm

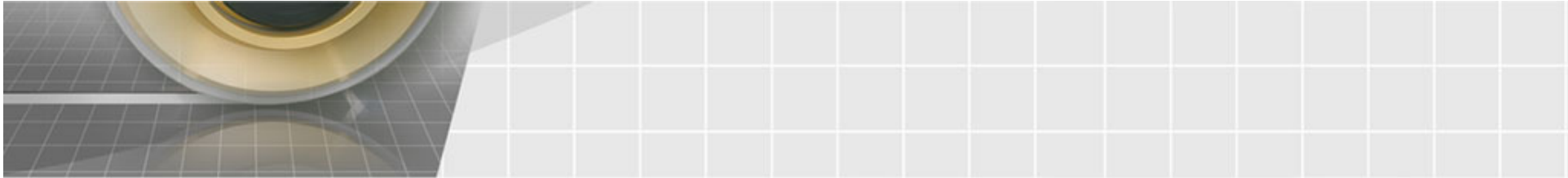
Dressing media P/N – 00767-0320-002 or - 003

<u>Dressing parameters</u>	Process
Spindle speed –	20-30Krpm
Feed rate – mm/sec	5, 10, 15, 20, 25, 30 x 4 cuts per F.R.
Cut depth – (mm)	Production + 0.2mm
Cut length – (Meters)	0.6 meter
Index –	Blade thickness x 2



Note – Perform height only after the dressing process is completed





## Application – Silicon wafers

Blade used – Nickel (Annular) 2” O.D. x 2-4, 3-6, 4-6mic. x .0012”-.002” thick

Dressing media – Silicon Carbide (Dark) 600 mesh

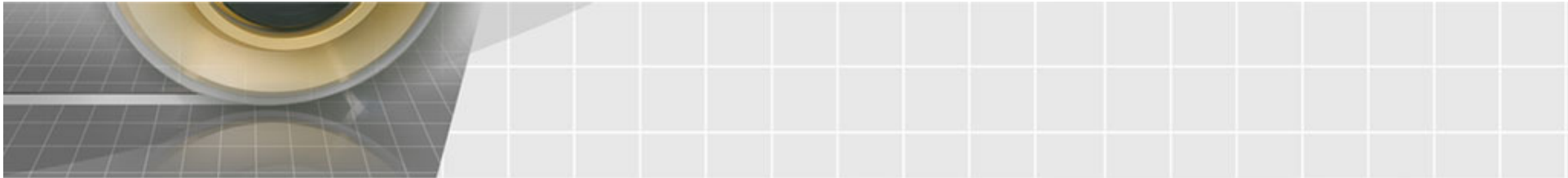
Dressing media geometry – 75 x 75 x 1mm

Dressing media P/N – 767-0000-001

<u>Dressing parameters:-</u>	Step # 1	Step # 2	Step # 3	Step # 4
Spindle speed –	35-45Krpm	35-45Krpm	35-45Krpm	35-45Krpm
Feed rate – inch/sec	6”	.2”	.5”	On blank Sil. wafer Start at .1”, cont. at .2” steps up to pro. speed depending on cut quality ✦
Cut depth -	.002”	Production + .002”	Production + .002”	
Cut length –	10 x 75=750mm	10 x 75=750mm	10 x 75=750mm	
Index –	Blade Thick. X 2	Blade Thick. X 2	Blade Thick. X 2	

✦ Cut depth = production depth + .001”

Note – Perform height only after the dressing process is completed



## Application – Silicon on Glass

Blade used – Resin – 2” O.D. x matrices QUP & QKP x 25-35mic. Grit  
x .006”-.010” thick

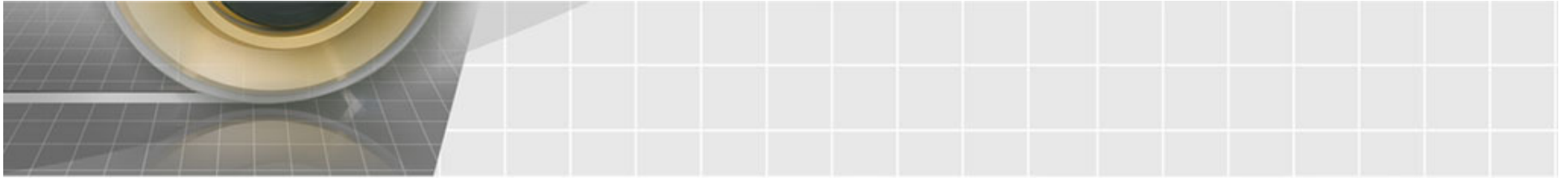
Dressing media – Silicon Carbide – 600 mesh

Dressing media geometry – 90 x 25 x 3 or 5mm

Dressing media P/N – 00767-0600-003 or -005

<u>Dressing parameters</u>	Process
Spindle speed – (Krpm)	25-30
Feed rate – mm/sec	1 x 2 cuts, 2 x 2 cuts 3 x 2 cuts, 5 x 2 cuts
Cut depth – (mm)	Production + 0.2mm
Cut length –	100mm
Index –	Blade Thickness x 2

**Note – Perform height only after the dressing process is completed**



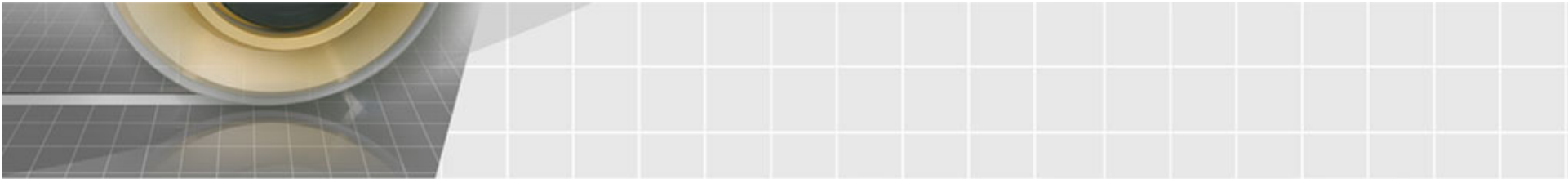
## Application – Tic – Magnetic head

### General:

This process involves thin blades with fine diamond grits. The quality criteria's are challenging and require unique dressing processes which are in house developed and are confidential for each customer.

The dressing process involves O.D. grinding on cylindrical grinders and than preliminary dressing on the dicing saws Using fine silicon carbide or Al. Oxide dressing medias and an override process on Tic. Blank material to confirm cut quality.

The following recommended dressing procedures were developed and used successfully in ADT during blade optimization for some key magnetic head customers.



## Application – Tic – Magnetic head

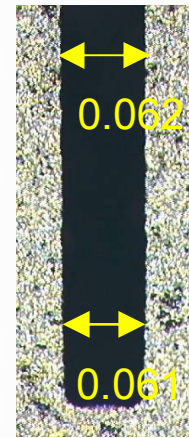
### Parting process

Blade used – Nickel – 4.3” O.D. x 3-6 & 4-6mic. Grit x special matrix  
x 0.060 – 0.100mm thick

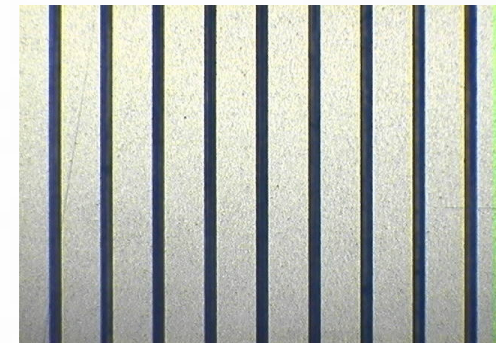
Dressing media – Silicon Carbide – 600 mesh

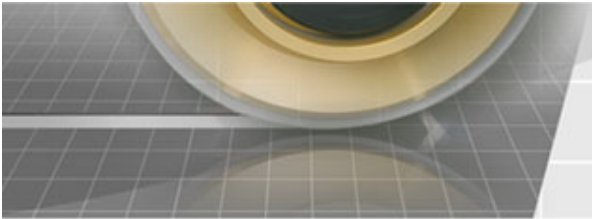
Dressing media geometry – 90 x 25 x 3mm

Dressing media P/N – 00767-0600-003



<u>Dressing parameters</u>	Process
Spindle speed – (Krpm)	9
Feed rate – mm/sec x Cut depth – (mm)	2 x 5 cuts x 0.050 c. depth 2 x 2 cuts x 0.550 c. depth
Cut length –	175mm
Index –	Blade Thickness x 3



- 
- Dressing – Silicon carbide 600 mesh
- Spindle – 9Krpm
  - 5x cuts at cut depth of – 0.050mm
  - 2x cuts at cut depth of – 0.550mm
  - Feed rate – 2mm/sec

## Application – Tic – Magnetic head

### Process: Row Slicing

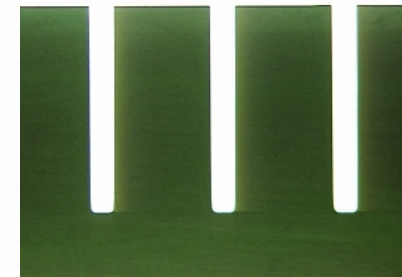
Blade used – Nickel – 4.3” O.D. x 4–8, 10, 13mic. Grit x special matrix  
x 0.090 – 0.120mm thick

Dressing media – Silicon Carbide – 600 mesh

Dressing media geometry – 90 x 25 x 3mm

Dressing media P/N – 00767-0600-003

<u>Dressing parameters</u>	Process
Spindle speed – (Krpm)	8 - 9
Feed rate – mm/sec x Cut depth – (mm)	2 x 6 cuts x 0.050 c. depth 2 x 2 cuts x 0.650 c. depth
Cut length –	200mm
Index –	Blade Thickness x 3



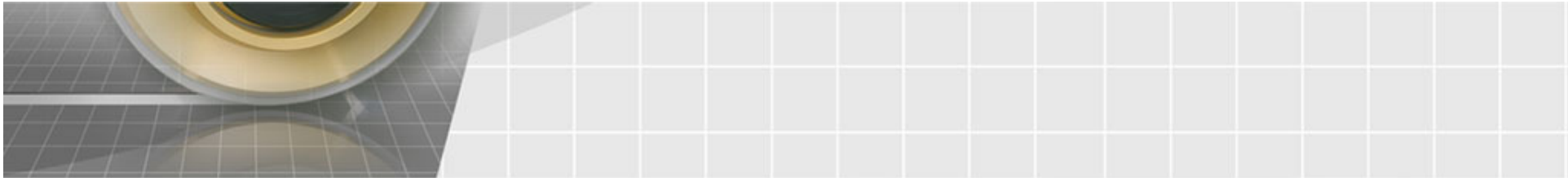


## Application – Green ceramic

Green ceramic or unfired ceramic requires a different dicing mechanism of using nickel electroformed blades or Tungsten carbide saw blades. Both with nickel blades and with T. carbide saw blades no dressing is required.

No real diamond exposing is needed on nickel blades and on T. carbide blades any dressing will actually damage the blade by losing the sharpness of the teeth.

So directly dicing production substrate can be performed



## Application – PZT (Ultrasound Sensors)

Blade used – Nickel – 2” O.D. x 3-6 & 4-8mic. Grit x Low Dia.%  
x 0.020– 0.075mm thick

Dressing media – Silicon Carbide – 600 mesh up to 3000 mesh

Dressing media geometry – 90 x 25 x 3mm 75 x 75 x 1mm and others

Most PZT customers developed their own dressing process which is  
Usually confidential. The bellow are generic guide lines for a new user.

<u>Dressing parameters</u>	Process
Spindle speed – (Krpm)	20-30
Feed rate on Sil C.– mm/sec x Cut depth – (mm)	2 x 5 cuts x 0.050 c. depth 2 x 2 cuts x prod. c. depth
On Sil. or PZT	Start at production F.R. (1-3mm/sec) x cut depth of 0.10mm. Change cut depth by steps of 0.050mm every 5 cuts till reaching production depth
Cut length – To be optimized	
Index – Blade Thick. x 3	